

Berkeley Sensor & Actuator Center (BSAC)



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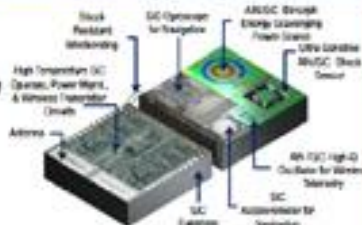
Harsh Environment and Telemetry Systems (HEaTS)





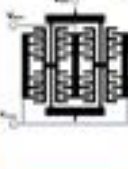

Sensors

MEMS integration




SIC-AIN Sensors

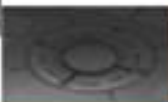
Resonant Strain Gauge



AIN Inertial sensors



AXL




Gyro

Harsh Environments

Subsurface & Combustion

Energy Industries	Geothermal	Oil & Gas Exploration	Industrial Gas Turbines	Automotive Engines	Aircraft Engines
					
	374°C	275°C	600°C	300°C	600°C
Measured Parameters	Pressure, Temperature, H ₂ S, Strain	Pressure, Temperature, Hydrocarbon Strain	Pressure, Temperature, Flame Speed, Acceleration	Pressure, Temperature, Flame Speed, O ₂	Pressure, Temperature, Flame Speed, Acceleration

64000 g Exposure (Shock!)




Labels: Before Shock, After Shock, Shock direction, Aluminum, MEMS die, Silicone Die, Polyimide, Solder Mount.

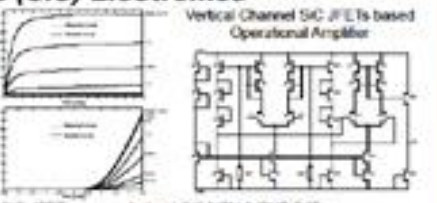
SiC ICs & RF Resonators

Silicon Carbide (SiC) Electronics


Vertical Channel Complementary SiC JFETs




Vertical Channel SiC JFETs based Operational Amplifier



Depletion Mode (DM) Lateral SiC JFETs

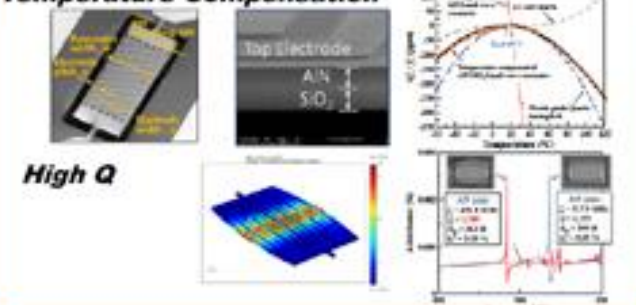


Lateral SiC NPN & PNP BJTs




Aluminum Nitride (AlN) Resonator Technology

Temperature Compensation

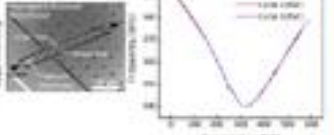


High Q

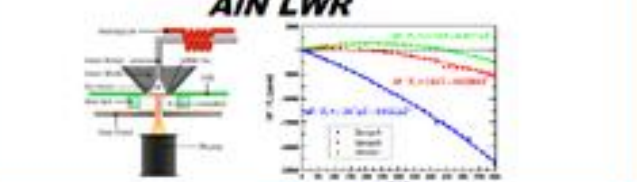
High Temperature SiC DETF



AIN DETF




AIN LWR



Fabrication & Materials

SiC on top of AlN



AlN etch

